

2A, 200V-1000V Fast Recovery Surface Mount Rectifier

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

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- Switch Mode Power Supply
- Inverters and Converters
- Free Wheeling diodes

MECHANICAL DATA

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1 whisker test
- · Polarity: Indicated by cathode band
- Weight: 0.06 g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _F	2	Α		
V_{RRM}	200-1000	V		
I _{FSM}	50	Α		
T _{J MAX}	150	°C		
Package	DO-214AC (SMA)			









DO-214AC (SMA)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL		RS2GA			RS2MA	UNIT
			-Т	-Т	-Т	-Т	-Т	
Marking code on the dev	vice vice		RS2DA	RS2GA	RS2JA	RS2KA	RS2MA	
Repetitive peak reverse	voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rn	Reverse voltage, total rms value		140	280	420	560	700	V
DC blocking voltage		V_{DC}	200	400	600	800	1000	V
Forward current		I _F	2				Α	
Surge peak forward current single half sine-	8.3 ms at T _A = 25°C				50			Α
wave superimposed on rated load per diode	1.0 ms at T_A = 25°C	I _{FSM}	124			А		
Junction temperature		T_J	-55 to +150				°C	
Storage temperature		T _{STG}	-55 to +150					°C



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance per diode	$R_{\Theta JL}$	14	°C/W		
Junction-to-ambient thermal resistance per diode	$R_{\Theta JA}$	86	°C/W		
Junction-to-case thermal resistance per diode	R _{eJC}	23	°C/W		

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		$I_F = 1A, T_J = 25^{\circ}C$		1.01	-	V
	DCODA TAR DCOCA T	I _F = 2A, T _J = 25°C		1.11	1.3	V
	RS2DA-T to RS2GA-T	I _F = 1A, T _J = 125°C		0.87	-	V
		I _F = 2A, T _J = 125°C		0.98	1.12	V
		I _F = 1A, T _J = 25°C		1.02	-	V
Forward voltage per diode (1)	DCC IA T	I _F = 2A, T _J = 25°C	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	1.12	1.3	V
	RS2JA-T	I _F = 1A, T _J = 125°C	V _F	0.91	-	V
		I _F = 2A, T _J = 125°C		1.01	1.07	V
		$I_F = 1A, T_J = 25^{\circ}C$		0.95	-	V
	RS2KA-T to RS2MA-T	I _F = 2A, T _J = 25°C		1.03	1.3	V
	R52KA-1 (0 R52MA-1	I _F = 1A, T _J = 125°C		0.81	-	V
		I _F = 2A, T _J = 125°C		0.90	1.03	V
Reverse current @ rated V _R per diode ⁽²⁾		T _J = 25°C		-	5	μA
		T _J = 125°C	l _R	-	100	μA
	RS2DA-T to RS2GA-T		t _{rr}	-	150	ns
Reverse recovery time	RS2JA-T	I _F =0.5A,I _R =1.0A, Irr=0.25A		-	250	ns
	RS2KA-T to RS2MA-T	0.20/1		-	500	ns
	RS2DA-T to RS2GA-T		CJ	14	-	pF
Junction capacitance per diode	RS2JA-T	1 MHz, V _R =4.0V		13	-	pF
uiouo	RS2KA-T to RS2MA-T			10	-	pF

Notes:

- (1) Pulse test with PW=0.3 ms
- (2) Pulse test with PW=30 ms

ORDERING INFORMATION					
ORDERING CODE	PACKAGE	PACKING			
RS2XA-T R3G ⁽¹⁾	SMA	1,800 / 7" Plastic reel			
RS2XA-T M2G ⁽¹⁾	SMA	7,500 / 13" Plastic reel			
RS2XA-T R2G ⁽¹⁾	SMA	7,500 / 13" Paper reel			

Notes:

(1) "X" defines voltage from 200V(RS2DA-T) to 1000V(RS2MA-T)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

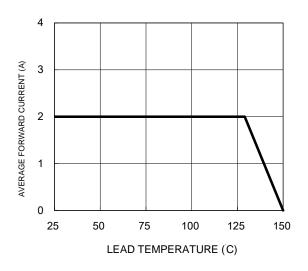


Fig.3 Typical Reverse Characteristics

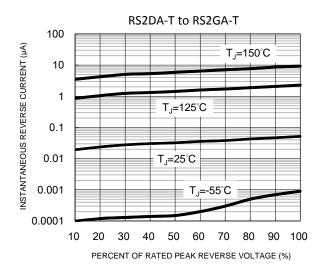


Fig.5 Typical Reverse Characteristics

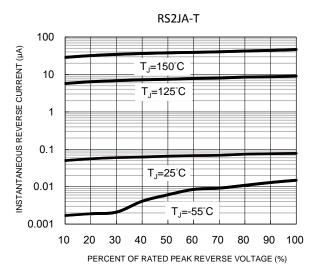


Fig.2 Typical Junction Capacitance

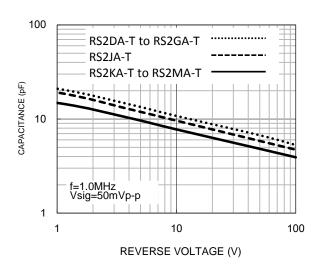


Fig.4 Typical Forward Characteristics

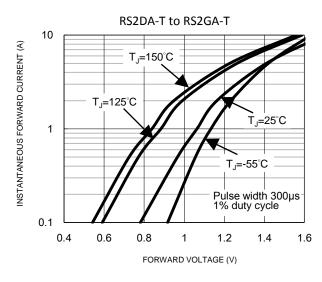
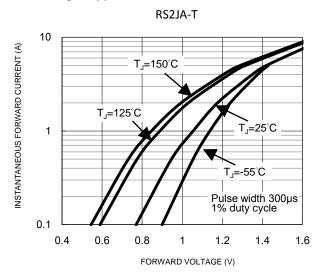


Fig.6 Typical Forward Characteristics



3 Version:A1904



Fig.7 Typical Reverse Characteristics

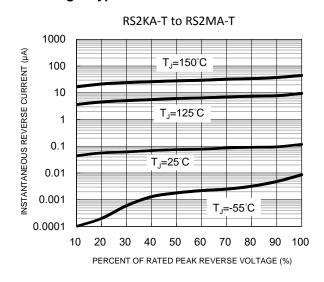


Fig.8 Typical Forward Characteristics

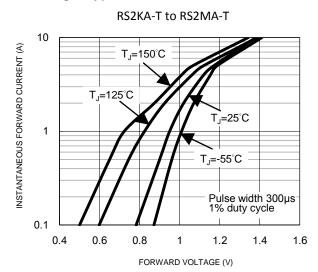
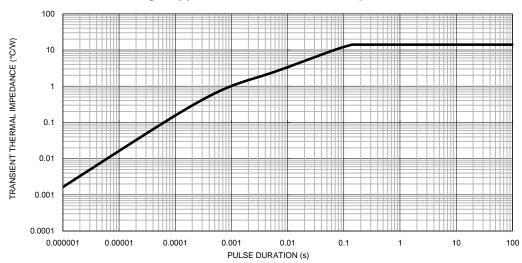


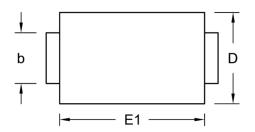
Fig.9 Typical Transient Thermal Impedance

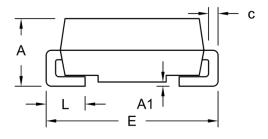




PACKAGE OUTLINE DIMENSIONS

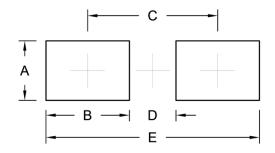
DO-214AC (SMA)





DIM.	Unit (mm)		Unit (inch)	
DIN.	Min.	Max.	Min.	Max.
Α	1.70	2.30	0.067	0.091
A1	0.05	0.20	0.002	0.008
b	1.20	1.80	0.047	0.071
С	0.15	0.41	0.006	0.016
D	2.40	3.00	0.094	0.118
E	4.80	5.40	0.189	0.213
E1	4.00	4.60	0.157	0.181
L	0.75	1.60	0.030	0.063

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.82	0.072
В	2.56	0.101
С	3.99	0.157
D	1.43	0.056
E	6.55	0.258

MARKING DIAGRAM



P/N = Marking Code G = Green Compound YW = Date Code

= Factory Code



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